OP07 Die Revision, Wafer Fabrication Site & Process Change

**Qualification Results Summary of OP07 Die Revision, Wafer Fabrication Site & Process Change**

| QUALIFICATION PLAN / STATUS | | | |
|---|---|---|---|
| **TEST** | **SPECIFICATION** | **SAMPLE SIZE** | **RESULTS** |
| Early Life Failure Rate (ELFR) | MIL-STD-883, M1015 | 4 x 500 | Pass |
| High Temperature Operating Life (HTOL) | JEDEC *JESD22-A108* | 3 x 77 | Pass |
| Highly Accelerated Stress Test (HAST)[1] | JEDEC *JESD22-A110* | 3 x 77 | Pass |
| Solder Heat Resistance (SHR)[1] | JEDEC *J-STD-020* | 1 x 30 | Pass |
| Temperature Cycle (TC)[1] | JEDEC *JESD22-A104* | 1 x 77 | Pass |
| Unbiased Highly Accelerated Stress Test (UHAST)[1] | JEDEC *JESD22-A118* | 1 x 77 | Pass |
| Latch-Up | JEDEC *JESD78* | 3/test | Pass ±200 mA, ±22.5 V |
| Electrostatic Discharge *Human Body Model*[2] | ESDA/JEDEC *JS-001-2011* | 3/voltage | Pass ±2000 V |
| Electrostatic Discharge *Field-Induced Charged Device Model* | JEDEC *JESD22-A114* | 3/voltage | Pass ±1250 V |

[1] Preconditioned per JEDEC J-STD-020 Level 1

[2] HBM testing shows the OP07 passes at all level between 750 V and 2 kV, but failures occur at 500 V.